

FEA Hotstamping B Pillar

Development of FEA Simulation Technology on Hotstamping B Pillar

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Key words : Hotstamping, FEA simulation, B Pillar

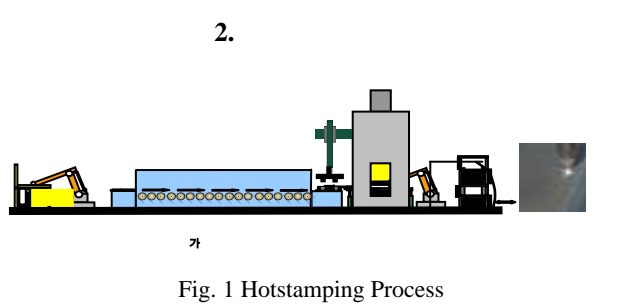
1.
Oil 가 , Co2
PNGV(Partnership for a new generation of vehicles) 1 34km 3 100km
FMVSS, ECE , IIHS(Insurance Institute for Highway Safety: RCAR(Research Council for Automobile Repairs)
(Hydroforming), Tube (TWB)
(Hotstamping)

Fig.1 가 , 가 , 가 , trim
Hole 가 가 가
950 930 가 . 가
, 930 가 가
850 가 가
3. 가

350 ~ 590MPa 850 가
1,500mpa 가 1,350 ~
30~50% 가
가 Springback
가
Pillar B

가 가 가 가 가
가 가 가
4. FEA Model
Punch
Blank Holder
Blank
Die
Fig. 2 FEA Model

FEA Model Hypermesh Mesh



(Fig.3)
(Heat Capacity), (Thermal Conductivity),
(Expansion Rate)
Table.1 Fig.4

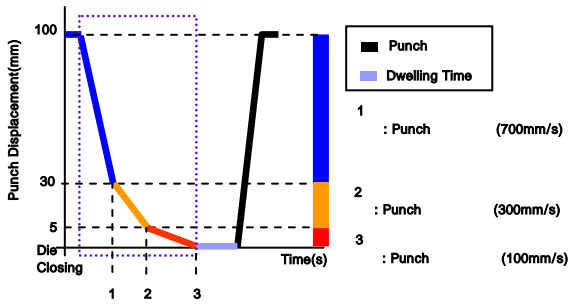


Fig. 3 Punch Closing Time

Table 1 FEA Simulation Factors

Blank Thickness	1.2t
Mesh	184,26
Holding Gap	0.3
Friction Coef.	0.125
Heat Capacity	4.86e+5 (J/Ton)
Thermal Conductivity	5.19e-2(W/mm)
Mechanical Equivalent of Heat	1e-3
Punch Moving (mm)	100
Holding Gap (mm)	0.3, 0.5
Die Temperature	20 (Prototyping base)
Blank Temperature	850

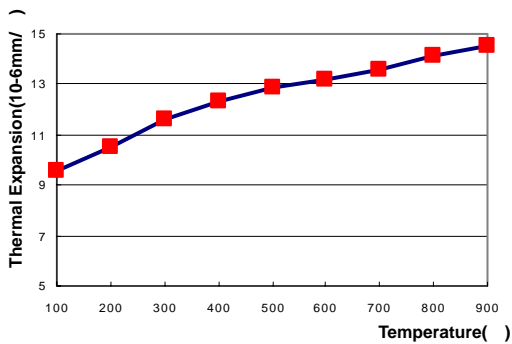


Fig.4 Thermal Expansion Rate

5.

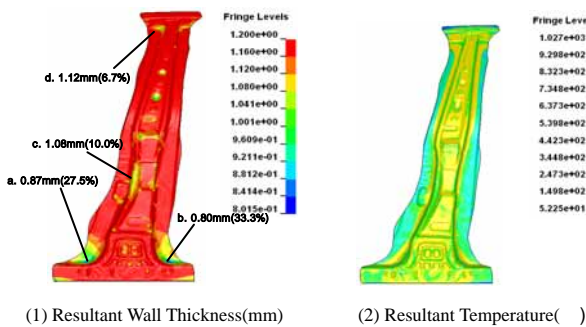


Fig.5 Simulation Result

Fig.5 a, b
가 33.3% 27.5%

Crack
500 ~ 700

6.

Fig.6

ProtoTyping Sample	Minimum Thk.(mm)	Thinning (%)	Remark
	1.16	3.3	Thickness Distribution 1.13 ~ 1.2mm
	1.17	2.5	
	1.13	5.8	
	0.90	25.0	Crack Occurred during proto-typing

Fig.6 Prototyping Result

7.

FLD

, Blank Size, Blank Holding
3D 가

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